

DOCUMENT NAME: PRODUCT SPECIFICATION SUBJECT: RF I BOARD END CONNECTOR

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PRODUCT SPECIFICATION

NO.SPEC-ANB-1001

RF I BOARD END CONNECTOR (Product NO. ANB0200*-12*)

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Date	2017-07-18	2017-07-18	2017-07-18	



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	***** RE	VISION HISTORY	****
Rev.	Date	Revision Page No.	Notes
A	2012-06-05	New Reversion	初次发行
В	2017-05-18	Update	更新发行
С			
D			
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1. SCOPE

This product described in this paper is a SMT Type Micro Coaxial RF Receptacle, whose part name in our comply is USS RF REC. It is special for micro strip-to -Coaxial adapter in RF circuit, such as Mobile Phone, Wireless Net, Mini PCI, Bluetooth, PDA, GPS, Electric Measurement Instruments and so on.

2. REQUIREMENT

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2.1. PRODUCT DIMENSION

Product shall be intermateable with industry standard product of opposite gender. This connector shall have the dimensions as shown in Drawing .

2.2. PCB/PANEL LAYOUT

The recommended PCB layout are shown in Drawing .

2.3. BILL OF MATERIAL

The bill of material and product number of Connectors are described in Drawing .

2.4. MECHANICAL & ELECTRICAL CHARACTERISTIC

The connector shall have the mechanical and electrical performance as described in Table I.

2.5. PACKAGING

Parts shall be packaged according to requirements specified in purchase order for safe delivery. Connector container and the packing specification are shown in Drawing .

2.6. HARMFUL MATERIAL CONTROL

Harmful material controls please follow the **Doc. No. QW-QA-10.**

3. PERFORMANCE AND TEST DESCRIPTION

3.1. REQUIREMENT

Product is designed to meet electrical, mechanical, and environmental performance requirements specified in **Table I**.

3.2. TEST CONDITION

Unless otherwise specified, all tests shall be performed at ambient environmental conditions:

3.2.1 Temperature: **15°C~35°C**

3.2.2 Humidity: **50±2% R.**

3.2.3 Atmospheric Pressure: 650 mmHg to 800 mmHg.

3.3. SAMPLE SELECTION

Test samples shall be selected at random from current production. No test samples shall be reused. Each group shall be containing **10** test samples.

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3.4 TEST SEQUENCE

Products qualification test sequence as shown in Table II.

4. QUALITY ASSURANCE PROVISIONS

CCT is responsible for the quality of the part as it is delivered to customer. The failing lots will be return or other supplier action.

5. PRODUCT PICTURE



6. Technical Parameters

6.1	Rated Voltage	60VAC (R.M.S)
6.2	Frequency Range	0~6GHz
6.3	Character Impedance	50 Ω
6.4	Operate Temperature	-40°C ~90°C
6.5	Operate Humidity	90% MAX
7. Elect	ric Performance	
7.1	Dielectric Resistance	500M Ω
7.2	Dielectric Withstand Voltage	200VAC 1Mi n
7.3	Contact Resistance	
	7.3.1 Signal Contact	Initial: 20m Ω max

7.3.2 Ground Contact Initial: $20m\Omega$ max

7.4 VSWR

\leq 3GHz	3~6GHz
1.3max	1.4max

7.4.1 Test Method(Refer to the FIG2):



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	Table I: Performance Requirements	S			
Items	Test Conditions	Specifications			
	Solder the receptacle connector to the test board and mate the plug connector together, then measure the contact resistance as shown in Fig3 by the four terminal methods. Apply the low level conditions in accordance with MIL-STD-202G, Method 307.	[Signal contact] Initial : $20m \Omega$ MAX After testing : $\Delta R20 m \Omega max$ [Ground contact]			
4	Open circuit voltage: 20 mV MAXCircuit current: 10 mA MAX	Initial $: 20m \Omega$ MAXAfter testing $: \Delta R20 m \Omega MAX$			
Contact Resistance	A B B Fig3	Signal connector =A-B Ground contact =D-C			
2. Insulation Resistance	Mate the receptacle and plug connector together, and then apply DC 100V between the signal contact and the ground contact in accordance with MIL-STD-202G, Method 302.	Initial :500M ହ MIN After testing :100 M ହ MIN			
3. Dielectric Withstanding Voltage	Mate the receptacle and plug connector together, and then apply AC 200V rms between the signal contact and the ground contact for a minute in accordance with MIL-STD-202G. Method 301	No creeping discharge, flashover no insulator breakdown shall occur.			
4. VSWR	Measure the VSWR as shown in FIG2 by the network analyzer. Frequency: 100M-6GHz	1.3MAX. at 0.1~3GHz 1.4MAX .at 3~6GHz			
5. Un-mating force	Solder the receptacle connector to the test board and mate the plug connector, then measure the un-mating force at speed 25 ± 3 mm/minutes along by the push-pull machine.	[Total un-mating force] Initial :4N MIN After 30 :2N MIN			
	Solder the receptacle connector to the test board, Push the receptacle connector from each directions as Shown in Fig.4. Measure the strength when the connector is broken.	20N MIN			
6. Receptacle shearing strength	Direction2	Block gage — 0.15mm leceptacle connector			

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7. Durability	Mate and un-mat the test board) ar 25 ± 3 mm/minute machine.	e the receptacle connector(soldered to nd plug connector 30 cycles at speed es along the mating by the push-pull	Appearar [Contact F Shall meet	nce] No abn Resistance] t Table I.1	ormality					
8. Contact resistance with force on the cable	Apply force on th During the testing discontinuity. Coaxial cable 4N MAX.	e cable as shown in Fig5 g, run 100mA DC to check electrical	Contact F [Appearar [Electrical No electric than 1 μ s s [Contact F Shall mee	nce] No abn discontinuity al discontinu shall occur. Resistance] et Table I.1	ormality /] uity grater	r				
9. Vibration	Apply the followir During the testir discontinuity. Frequency: 10Hz Half amplitude, I 59m/s ² (6G) Directions, cycle cycles about eac	Fig5Apply the following vibration to the mating connector.During the testing, run 100mA DC to check electricaldiscontinuity.Frequency: 10Hz \rightarrow 100 Hz \rightarrow 10Hz/approx 20 minutes.Half amplitude, Peak value of acceleration : 1.5mm or 59m/s² (6G)Directions, cycle: 3 mutually perpendicular direction,3								
10. Shock	Cycles about each direction. Apply the following vibration to the mating connector. During the testing, run 100mA DC to check electrical discontinuity. Peak value of acceleration: 735 m/s² (75G) Duration :11msec Wave Form :half sinusoidal Direction, cycle :6 mutually perpendicular direction,									
11. Humidity (Steady State)	Apply the followir in accordance wi Condition B. Temperature Humidity Duration :	ng environment to the mating connector th MIL-STD-202G,Method 103, : 313±2K (40±2℃) : 90~95%RH 96 hours	[Appearan [Contact F Shall mee [Insulation Shall mee [Dielectric Shall mee	nce] No abn Resistance] et Table I.1 n Resistance et Table I.2 Withstandin et Table I.3.	ormality] g Voltage	9]				
12. Thermal Shock	Apply the followir in accordance wi Condition A. Temperature Transition time No. of cycles	ng environment to the mating connector th MIL-STD-202G,Method 107G, : 218K (-55℃) →358K(85℃): 30min : 5min. MAX : 5 cycles	[Appearan [Contact F Shall mee [Insulation Shall mee [Dielectric Shall mee	nce] No abn Resistance] et Table I.1 n Resistance et Table I.2 Withstandin et Table I.3.	ormality] g Voltage	•]				

DOCUMENT NAME: PRODUCT SPECIFICATION SUBJECT: RF I BOARD END CONNECTOR 13. High Temperature Life Apply the following environment to the mating connecto Temperature : 363±2K (90±2°C) Duration : 96 hours 14. H2S Gas Apply the following environment to the mating connecto in accordance with MIL-STD-202G,Method 101E, Condition B. 15. Salt Water Spray Apply the following environment to the mating connecto in accordance with MIL-STD-202G,Method 101E, Condition B. 16. Solder ability Dip the solder tine of the contacts in the solder bath 518 ± 5K(245 ± 5°C) for 5 ± 0.5seconds after immersir the tine in the flux of RMA type for 5 to 10 seconds. 17. Soldering Heat Resistance (1) Reflow part : 533+0/-5K(260+0/-5°C) Peak 498K MIN .(225°CMIN) 70sce.MIN (2) Pre-heat part: 433~443K (160~170°C) 80~100se · Refer to reflow temperature profile.(Fig6) · The number of reflow is within 2 times. 17. Soldering Heat Resistance Yamuan of the solder time of the contacts in the solder time file is the number of reflow is within 2 times.	DOCUMENT NO: SPEC-ANB-1001						
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13. High Temperature Life	Apply the followir Temperature Duration :	ng environment to the mating connector : 363±2K (90±2℃) : 96 hours	Appearan Contact I Shall me Insulation Shall me	nce] No abn Resistance] et Table I.1 n Resistance et Table I.2 withstandin	ormality	•]	
14. H₂S Gas	Apply the followir Temperature Relative Humidity Duration	ng environment to the mating connector : 313±2K (40±2℃) y : 80±5%RH : 96 hours	[Appearat [Contact I Shall me [Insulation Shall me [Dielectric	nce] No abn Resistance] et Table I.1 n Resistance et Table I.2 c Withstandin	ormality] g Voltage	e]	
15. Salt Water Spray	Apply the followir in accordance wir Condition B. Temperature Relative Humidity Salt water density Duration	ng environment to the mating connector th MIL-STD-202G,Method 101E, : 308±2K (35±2℃) y : 95~98%RH y : 5±1%(by weight) : 48 hours	[Appeara [Contact I Shall me	nce] No abn Resistance] et Table I.1	ormality		
16. Solder ability	Dip the solder tin 518 \pm 5K(245 \pm 5 the tine in the flux	ne of the contacts in the solder bath a 5° C) for 5 ± 0.5 seconds after immersin x of RMA type for 5 to 10 seconds.	at More than surface sha g5%of the pi gather at a	95%of the dip all be wet and inhole than sl point.	ped I less tha nall not	n	
	 (1) Reflow part = MIN .(225℃N (2) Pre-heat part * Refer to r * The numb 	: 533+0/-5K(260+0/-5℃) Peak 498K MIN) 70sce.MIN t: 433~443K(160~170℃) 80~100se eflow temperature profile.(Fig6) ber of reflow is within 2 times.	c No abnorm the perform	nality adverse nance shall no (260°C)	ely affecti ot occur.	ing	
17. Soldering Heat Resistance	<u>Fig 6</u>	498K (225°C) 433~443K (160~170°C) 80~100sec. Time (sec	70sec.	1sec.			

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Table II: Test Sequence and Sample Quantity														
Test:	•	B			E	F	6	u			K		М	N
	A	P					G	п		J	n	╞	IVI	
1 Contact														
Resistance				1,3	1,3	1,3	1,3	1,5	1,5	1,3	1,3	1,3		
2.Insulation Resistance				,				2,6	2,6			,		
3.Dielectric Withstanding Voltage								3,7	3,7					
4.VSWR	1													
5.Un-mating force		1												
6. Receptacle shearing strength			1											
7.Durability				2										
8.Contact resistance with force on the cable					2									
9.Vibration						2								
10.Shock							2							
11.Humidity (Steady State)								4						
12. Thermal Shock									4					
13. High Temperature Life										2				
14.H₂S Gas											2			
15. Salt Water Spray												2		
16. Solder ability													1	
17.Soldering Heat Resistance														1
Sample QTY.	10	10	10	10	10	10	10	10	10	10	10	10	10	10

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